

03-29-2006

Client Code: SDISW.012AUS



103207017


To the Director, U.S. Patent and Trademark Office, please record the attached original documents or copy thereof.

112948 U.S. PTO
11/385097



032006

03/20/06

<p>1. Name of conveying party(ies): (List using letters or numbers for multiple parties)</p> <p>Tae-Wook Kang</p> <p>Additional name(s) of conveying party(ies) attached?</p> <p>() Yes (X) No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: SAMSUNG SDI CO., LTD.</p> <p>Internal Address:</p> <p>Street Address: 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, REPUBLIC OF KOREA</p> <p>Additional name(s) of receiving party(ies) attached?</p> <p>() Yes (X) No</p>
<p>3. Nature of conveyance:</p> <p>(X) Assignment () Security Agreement</p> <p>() Merger () Change of Name</p> <p>() Other:</p> <p>Execution Date: (List as in section 1 if multiple signatures)</p> <p>March 20, 2006</p>	<p>4. US or PCT Application number(s) or US Patent number(s):</p> <p>(X) Application(s) filed herewith</p> <p>Additional numbers attached?</p> <p>() Yes (X) No</p>
<p>5. Party to whom correspondence concerning document should be mailed:</p> <p>Customer No. 20,995</p> <p>Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14th Floor Irvine, CA 92614</p> <p>Return Fax: (949) 760-9502</p> <p>Attorney's Docket No.: SDISW.012AUS</p>	<p>6. Total number of applications and patents involved: 1</p>
<p>7. Total fee (37 CFR 1.21(h)): \$40</p> <p>(X) Enclosed</p>	<p>8. Deposit account number: 11-1410</p> <p>Please charge this account for any additional fees which may be required, or credit any overpayment to this account.</p>
<p>9. Statement and signature.</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.</p> <p><u>Mincheol Kim</u> Name of Person Signing</p> <p> Signature</p> <p><u>3/20/06</u> Date</p> <p>51,306 Registration No.</p> <p>Total number of pages including cover sheet, attachments and document: 2</p>	

Documents transmitted via Mail to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Director, U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

03/23/2006 LWONDIMI 00000018 11385097

04 FC:8021

40.00

2460406_1
032006

Application No.: Unknown
Filing Date: Herewith

PATENT
Client Code:SDISW.012AUS
Page 1

ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements in an **ORGANIC LIGHT EMITTING DIODE AND METHOD OF MANUFACTURING THE SMAE**, the specification of which was executed on even date herewith.

AND WHEREAS, **Samsung SDI Co., Ltd.**, (hereinafter "ASSIGNEE"), with its principal place of business at **575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea**, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date: March 20, 2006

Signature: TaeWook Kang

Name: Tae-Wook KANG

Address : c/o Samsung SDI Co., Ltd.

575 Shin-dong, Yeongtong-gu, Suwon-si,

Gyeonggi-do, Republic of Korea

1888122
082405